

5 **LAND GRID ARRAY (LGA) PAD REPAIR STRUCTURE AND METHOD**

ABSTRACT

A method and structure to repair or modify a land grid array (LGA) interface mounted on a printed circuit card. The land grid array interface has a plurality of contact pads on a first surface of the printed circuit card, each contact pad is connected to at least one electronic component by a conductor. The method includes, for a preselected one of the contact pads to be replaced, drilling a first hole through printed circuit card at a predetermined location and having a first diameter predetermined to be sufficient to electrically isolate the preselected contact pad from all circuits contained in or on the printed circuit card. If any of the preselected contact pad or any conductor material directly attached to it remains attached to the first surface, it is delaminated, thereby separating it from the first surface of the printed circuit card. A preformed replacement conductor/contact pad structure is installed, such that one end of the structure having a replacement contact pad is positioned on the first surface of the printed circuit card at the location of the removed preselected contact pad. The second end of the replacement structure is electrically connected to at least one predetermined electronic component or layer, thereby completing the repair or modification.

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